



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Parameter	Ratings	Units
Blocking Voltage	280	V_P
Load Current	200	mA_{rms} / mA_{DC}
On-Resistance (max)	10	Ω

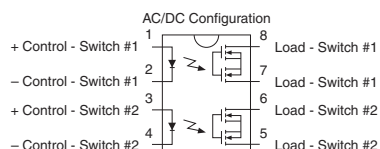
Features

- 500 μs Maximum Switching Times
- High Performance 280V_P Blocking Voltage
- High Reliability
- 3750V_{rms} Input/Output Isolation
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- FCC Compatible
- VDE Compatible
- Low Drive Power Requirements (TTL/CMOS Compatible)
- Small 8-pin Package
- Machine Insertable, Wave Solderable
- Surface Mount Tape & Reel Versions Available

Applications

- Telecommunications
 - Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hook Switch
 - Dial Pulsing
 - Ground Start
 - Ringing Injection
- Instrumentation
 - Test Equipment
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Pin Configuration



Description

PAA127 is a dual high performance 280V, 200mA, 10 Ω , normally open (1-Form-A) Solid State Relay that has two independently controlled, optically coupled MOSFET switches in an 8-pin package. It employs optically coupled MOSFET technology to provide 3750V_{rms} of input to output isolation.

Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient GaAlAs infrared LED.

This dual single-pole OptoMOS relay provides a more compact design solution than discrete single-pole relays in a variety of applications, and saves board space by incorporating both switches in a single 8-Pin package.

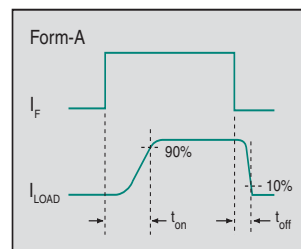
Approvals

- UL Recognized Component: File # E76270
- CSA Certified Component: Certificate # 1175739
- Certified to:
 - IEC 60950-1: 2005
 - EN 60950-1: 2006
 - TUV Certificate # B 12 11 82667 002

Ordering Information

Part #	Description
PAA127	8-Pin DIP (50/Tube)
PAA127S	8-Pin Surface Mount (50/Tube)
PAA127STR	8-Pin Surface Mount (1,000/Reel)
PAA127P	8-Pin Flatpack (50/Tube)
PAA127PTR	8-Pin Flatpack (1,000/Reel)

Switching Characteristics of Normally Open Devices



Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	280	V _P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation ¹	150	mW
Total Power Dissipation ²	800	mW
Isolation Voltage, Input to Output	3750	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33 mW / °C

² Derate linearly 6.67 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Electrical Characteristics @ 25°C

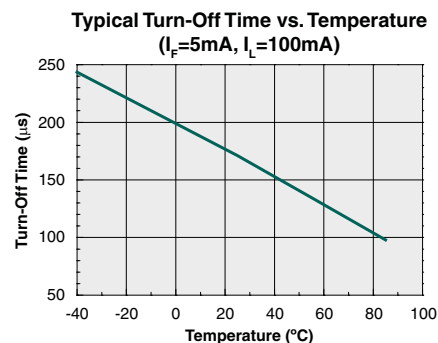
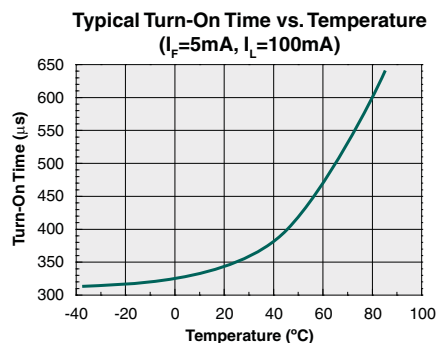
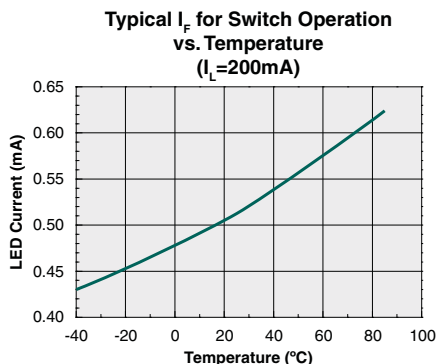
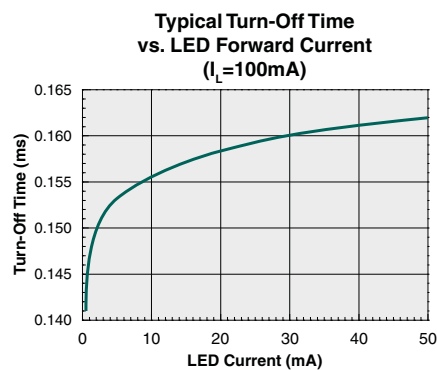
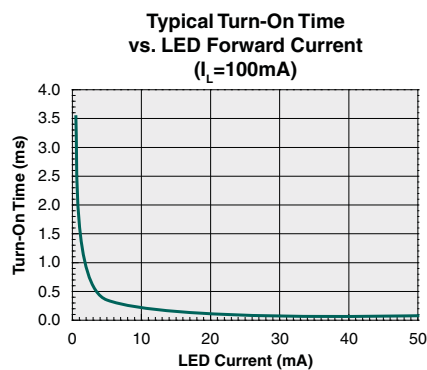
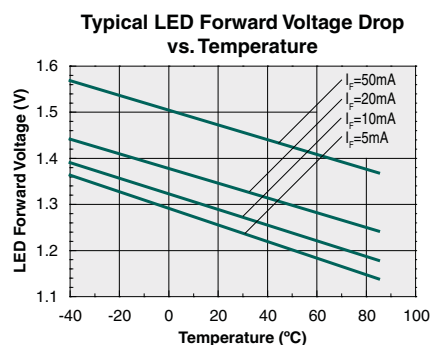
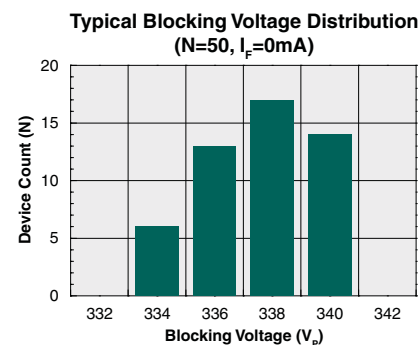
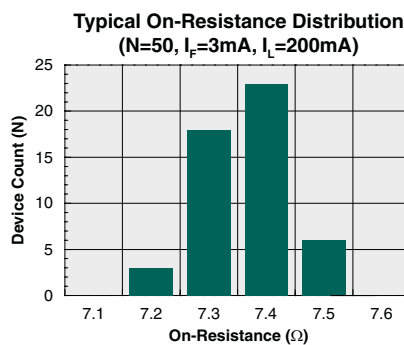
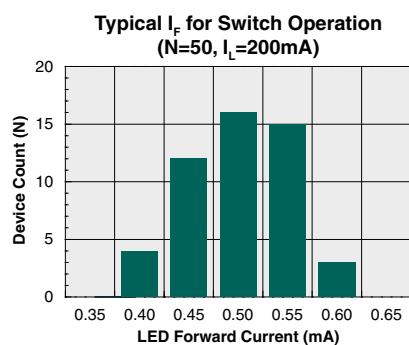
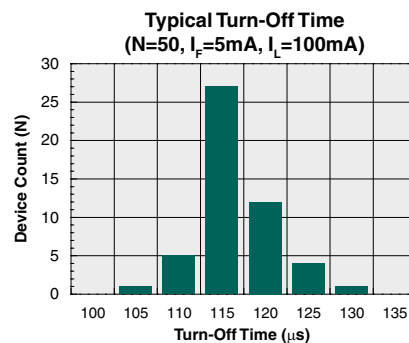
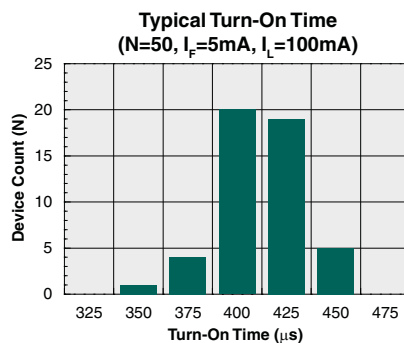
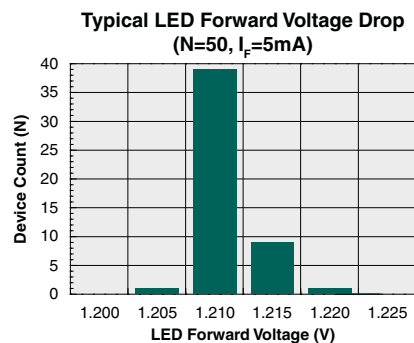
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current						
Continuous ¹	-	I _L	-	-	200	mA _{rms} / mA _{DC}
Peak	t = 10ms	I _{LPK}	-	-	±400	mA _P
On-Resistance ²	I _F =3mA, I _L =200mA	R _{ON}	-	7.3	10	Ω
Off-State Leakage Current	I _F =0mA, V _L =280V _P	I _{LEAK}	-	1	25	nA
Switching Speeds						
Turn-On	I _F =5mA, V _L =10V	t _{on}	-	0.42	0.5	ms
Turn-Off		t _{off}	-	0.12	0.5	
Output Capacitance	I _F =0mA, V _L =50V, f=1MHz	C _{OUT}	-	16	-	pF
Input Characteristics						
Input Control Current to Activate ³	I _L =200mA	I _F	-	0.5	3	mA
Input Control Current to Deactivate	-	-	0.3	0.49	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Common Characteristics						
Input to Output Capacitance	-	C _{IO}	-	3	-	pF

¹ If both poles operate, the load current must be derated in order not to exceed the package power dissipation value.

² Measurement taken within one (1) second of on-time.

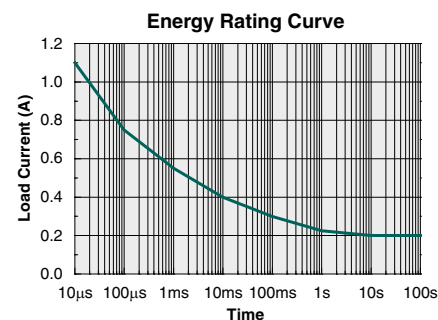
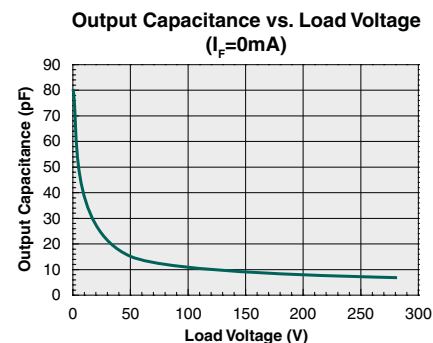
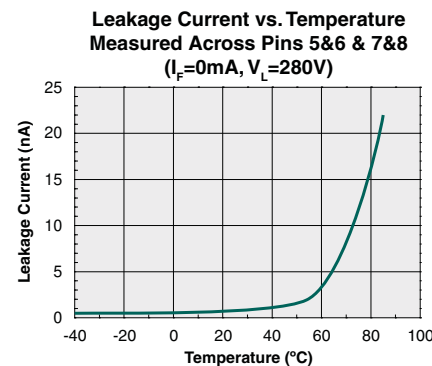
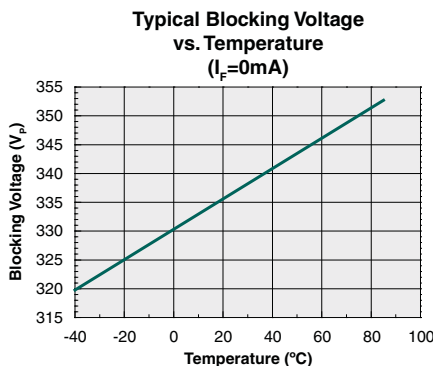
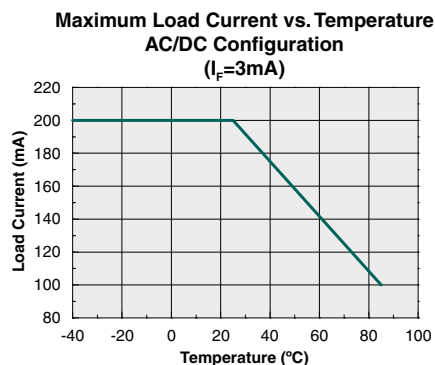
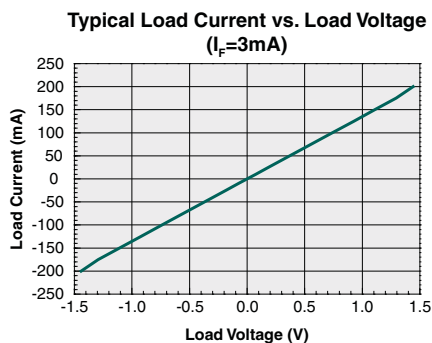
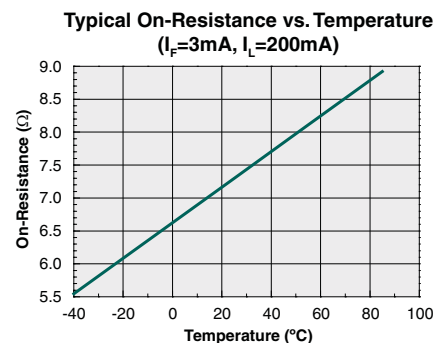
³ For high-temperature applications (>60°C) use a LED current of at least 5mA.

PERFORMANCE DATA @25°C (Unless Otherwise Noted)*



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

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Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
PAA127 / PAA127S / PAA127P	MSL 1

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
PAA127 / PAA127S	250°C for 30 seconds
PAA127P	260°C for 30 seconds

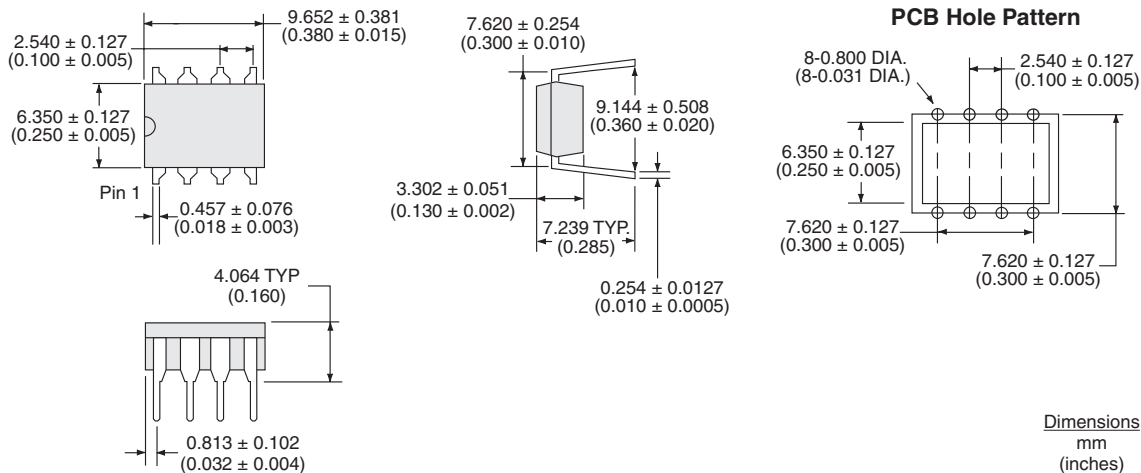
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

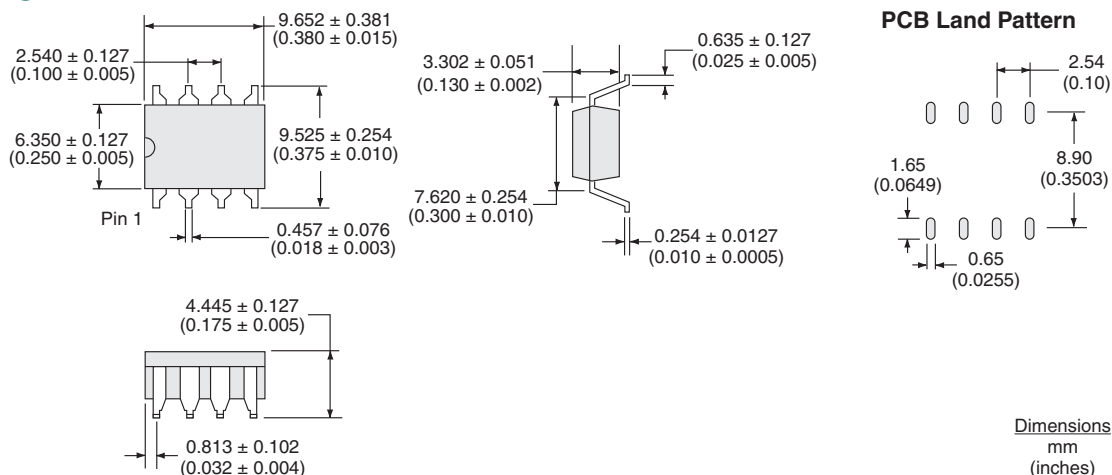


MECHANICAL DIMENSIONS

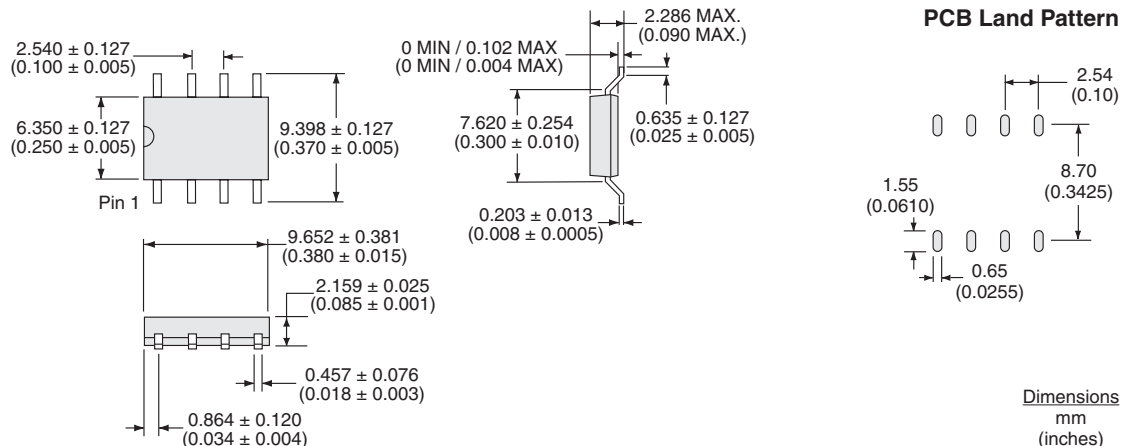
PAA127



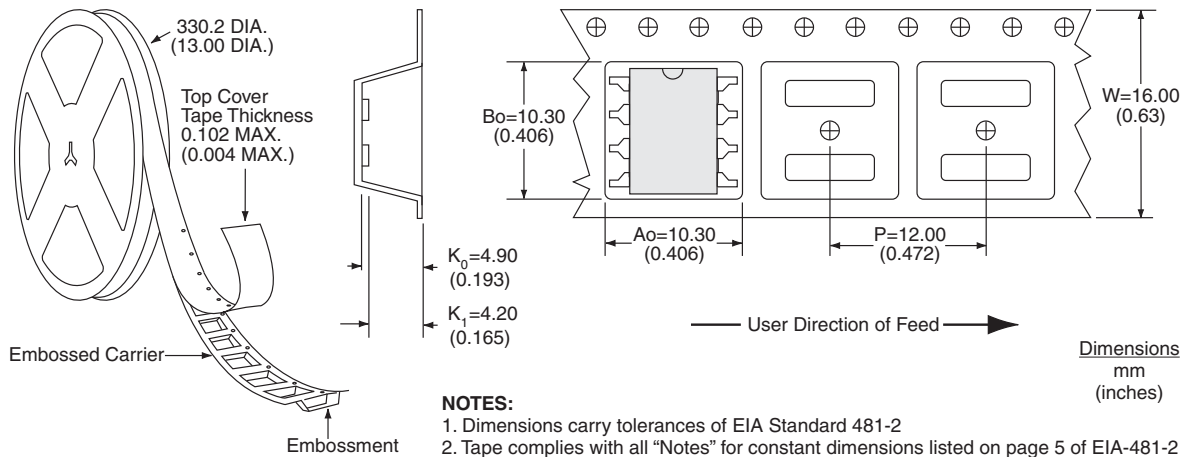
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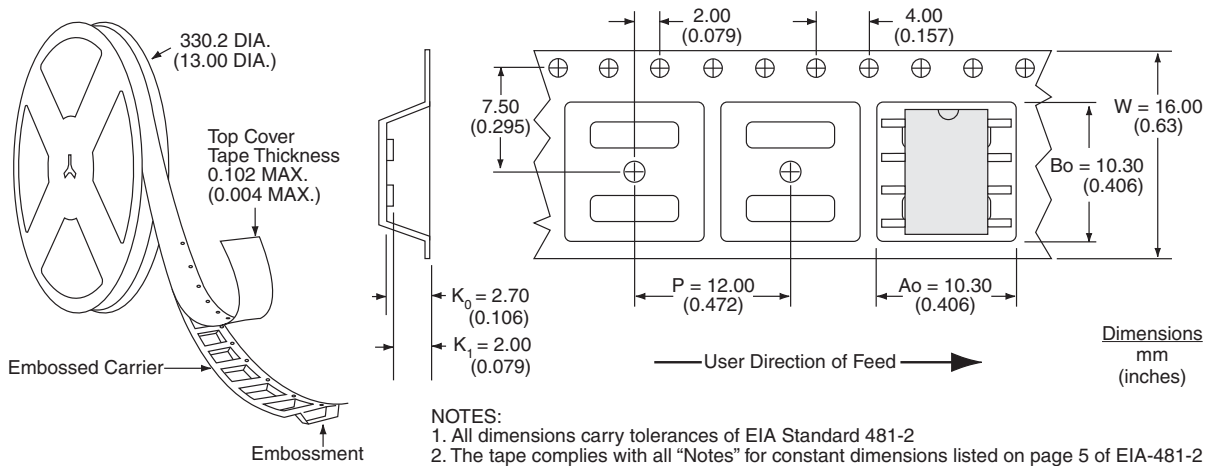
PAA127P



PAA127STR Tape & Reel



PAA127PTR Tape & Reel



For additional information please visit our website at: www.ixysic.com

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